NC7S08

TinyLogic HS 2-Input AND Gate

ON Semiconductor®

www.onsemi.com

Description

The NC7S08 is a single 2−Input high performance CMOS AND Gate. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation over a broad V_{CC} range. ESD protection diodes inherently guard both inputs and output with respect to the V_{CC} and GND rails. Three stages of gain between inputs and outputs assures high noise immunity and reduced sensitivity to input edge rate.

Features

- Space Saving SC−74A and SC−88A 5−Lead Package
- Ultra Small MicroPak™ Leadless Package
- High Speed: t_{PD} = 3.5 ns Typ
- Low Quiescent Power: I_{CC} < 1 μA
- Balanced Output Drive: 2 mA I_{OL}, −2 mA I_{OH}
- Broad V_{CC} Operating Range: 2 V – 6 V
- Balanced Propagation Delays
- Specified for 3 V Operation
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

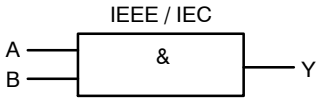
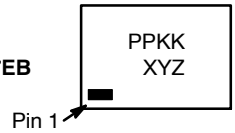
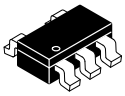


Figure 1. Logic Symbol

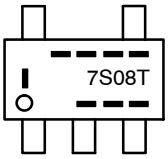
MARKING DIAGRAMS

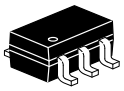
SIP6
CASE 127EB



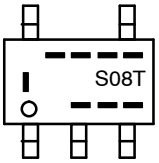


SC−74A
CASE 318BQ





SC−88A
CASE 419AC−01



PP, 7S08, S08 = Specific Device Code
KK = 2−Digit Lot Run Traceability Code
XY = 2−Digit Date Code Format
Z = Assembly Plant Code
T = Die Run Code
▬▬▬ = Year Coding Scheme
▌▪▬ = Plant Code Identifier
▬▬▬ = Eight−Week Datacoding Scheme

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

Pin Configurations

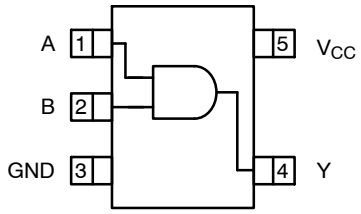


Figure 2. SC−88A and SC−74A (Top View)

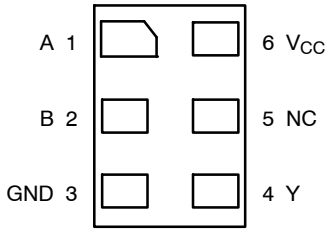


Figure 3. MicroPak (Top Through View)

PIN DESCRIPTION

Pin Names	Description
A, B	Inputs
Y	Output
NC	No Connect

FUNCTION TABLE (Y = AB)

Inputs		Output
A	**B**	**Y**
L	L	L
L	H	L
H	L	L
H	H	H

H = HIGH Logic Level
L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage		−0.5	6.5	V
I_{IK}	DC Input Diode Current	$V_{IN} \le -0.5$ V	−	−20	mA
		$V_{IN} \ge V_{CC} + 0.5$ V	−	+20	
V_{IN}	DC Input Voltage		−0.5	V_{CC} + 0.5	V
I_{OK}	DC Output Diode Current	$V_{OUT} < -0.5$ V	−	−20	mA
		$V_{OUT} > V_{CC} + 0.5$ V	−	+20	
V_{OUT}	DC Output Voltage		−0.5	V_{CC} + 0.5	V
I_{OUT}	DC Output Source or Sink Current		−	±12.5	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin		−	±25	mA
T_{STG}	Storage Temperature		−65	+150	°C
T_J	Junction Temperature		−	+150	°C
T_L	Lead Temperature (Soldering, 10 Seconds)		−	+260	°C
P_D	Power Dissipation in Still Air	SC−74A	−	225	mW
		SC−88A−5	−	190	
		MicroPak	−	327	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		2.0	6.0	V
V_{IN}	Input Voltage		0	V_{CC}	V
V_{OUT}	Output Voltage		0	V_{CC}	V
T_A	Operating Temperature		−40	+85	°C
t_r, t_f	Input Rise and Fall Times	V_{CC} at 2.0 V	0	20	ns
		V_{CC} at 3.0 V	0	20	
		V_{CC} at 4.5 V	0	10	
		V_{CC} at 6.0 V	0	5	
θ_{JA}	Thermal Resistance	SC−74A	–	555	°C/W
		SC−88A−5	–	659	
		MicroPak	–	382	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

DC ELECTICAL CHARACTERISTICS

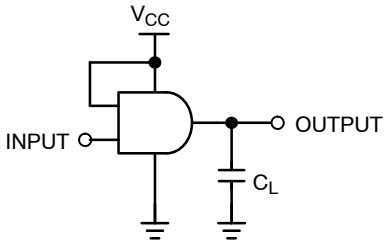
Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C			T_A = −40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	HIGH Level Input Voltage	2.0		1.50	–	–	1.50	–	V
		3.0 – 6.0		0.7 x V_{CC}	–	–	0.7 x V_{CC}	–	
V_{IL}	LOW Level Input Voltage	2.0		–	–	0.50	–	0.50	V
		3.0 – 6.0		–	–	0.3 x V_{CC}	–	0.3 x V_{CC}	
V_{OH}	HIGH Level Output Voltage	2.0	I_{OH} = −20 μA, V_{IN} = V_{IH}	1.90	2.0	–	1.90	–	V
		3.0		2.90	3.0	–	2.90	–	
		4.5		4.40	4.5	–	4.40	–	
		6.0		5.90	6.0	–	5.90	–	
		3.0	V_{IN} = V_{IH}, I_{OH} = −1.3 mA	2.68	2.85	–	2.63	–	
		4.5	V_{IN} = V_{IH}, I_{OH} = −2 mA	4.18	4.35	–	4.13	–	
		6.0	V_{IN} = V_{IH}, I_{OH} = −2.6 mA	5.68	5.85	–	5.63	–	
V_{OL}	LOW Level Output Voltage	2.0	I_{OL} = 20 μA, V_{IN} = V_{IL}	–	0.0	0.10	–	0.10	V
		3.0		–	0.0	0.10	–	0.10	
		4.5		–	0.0	0.10	–	0.10	
		6.0		–	0.0	0.10	–	0.10	
		3.0	V_{IN} = V_{IH} or V_{IL}, I_{OH} = 1.3 mA	–	0.1	0.26	–	0.33	
		4.5	V_{IN} = V_{IH} or V_{IL}, I_{OL} = 2 mA	–	0.1	0.26	–	0.33	
		6.0	V_{IN} = V_{IH} or V_{IL}, I_{OL} = 2.6 mA	–	0.1	0.26	–	0.33	
I_{IN}	Input Leakage Current	6.0	V_{IN} = V_{CC}, GND	–	–	±0.1	–	±1.0	μA
I_{CC}	Quiescent Supply Current	6.0	V_{IN} = V_{CC}, GND	–	–	1.0	–	10.0	μA

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C			T_A = −40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay (Figure 4, 6)	5.0	C_L = 15 pF	–	3.5	15	–	–	ns
		2.0	C_L = 50 pF	–	20	100	–	125	
		3.0		–	11	27	–	35	
		4.5		–	8	20	–	25	
		6.0		–	7	17	–	21	
t_{TLH}, t_{THL}	Output Transition Time (Figure 4, 6)	5.0	C_L = 15 pF	–	3.0	10	–	–	ns
		2.0	C_L = 50 pF	–	25	125	–	155	
		3.0		–	16	35	–	45	
		4.5		–	11	25	–	31	
		6.0		–	9	21	–	26	
C_{IN}	Input Capacitance	Open		–	2	10	–	10	pF
C_{PD}	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	–	6	–	–	–	pF

2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD} = (C_{PD})\ (V_{CC})\ (f_{IN}) + (I_{CC}static)$.

AC Loading and Waveforms



C_L includes load and stray capacitance
Input PRR = 1.0 MHz, t_W = 500 ns

Figure 4. AC Test Circuit

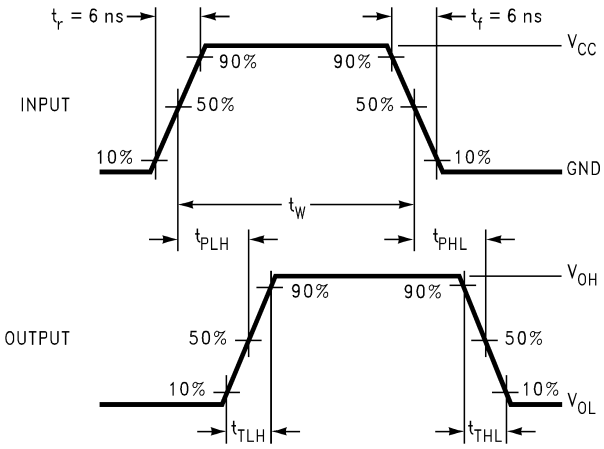
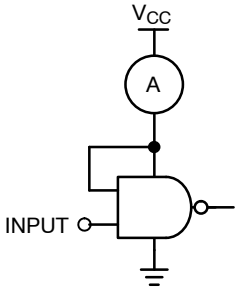


Figure 6. AC Waveforms



Input = AC Waveform;
PRR = Variable; Duty Cycle = 50%.

Figure 5. I_{CCD} Test Circuit

DEVICE ORDERING INFORMATION

Device	Top Mark	Packages	Shipping†
NC7S08M5X	7S08	SC−74A	3000 / Tape & Reel
NC7S08P5X	S08	SC−88A	3000 / Tape & Reel
NC7S08L6X	PP	SIP6, MicroPak	5000 / Tape & Reel

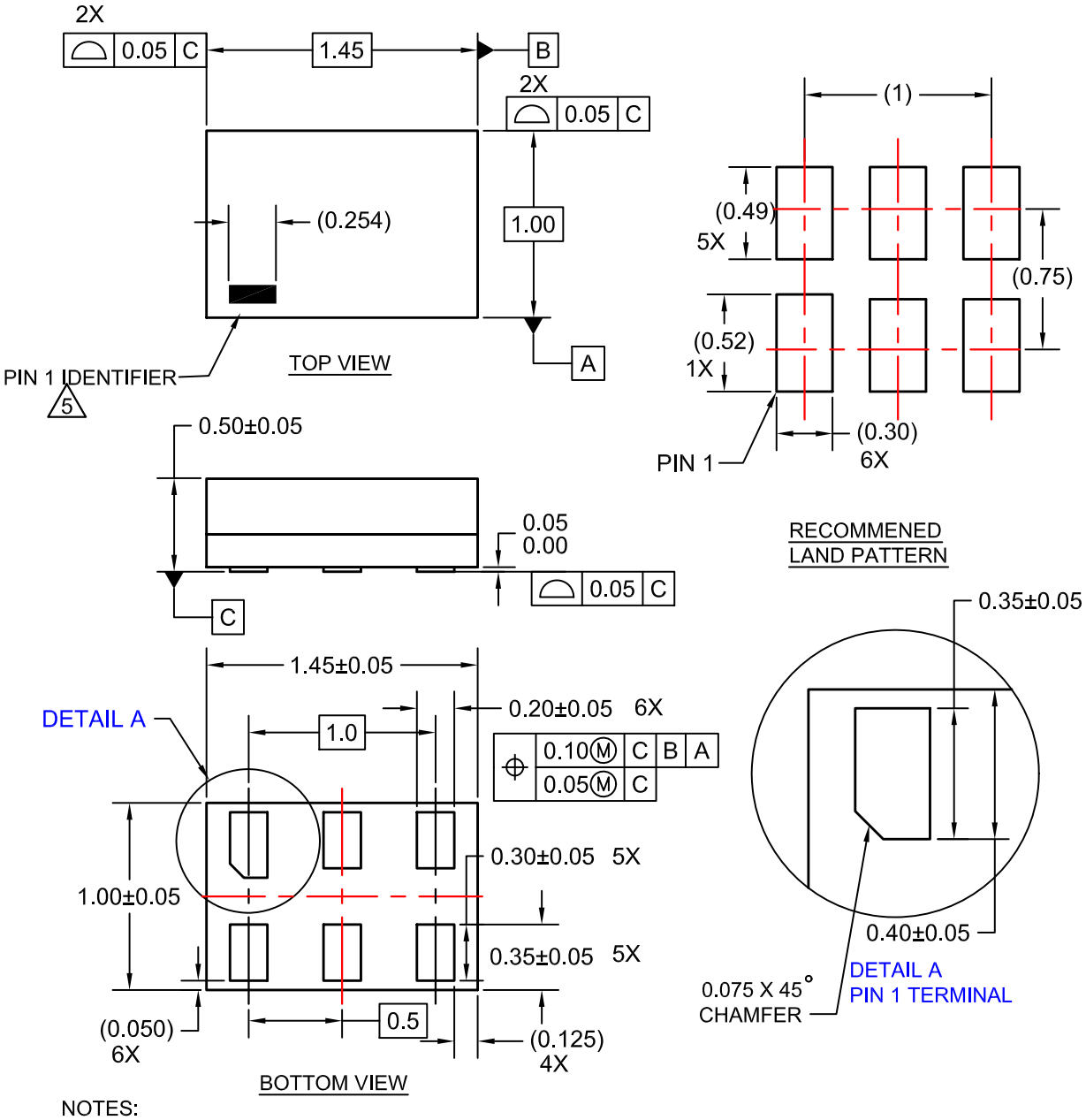
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

SIP6 1.45X1.0
CASE 127EB
ISSUE O

DATE 31 AUG 2016



NOTES:

1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

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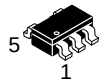
DESCRIPTION:	**SIP6 1.45X1.0**	**PAGE 1 OF 1**

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

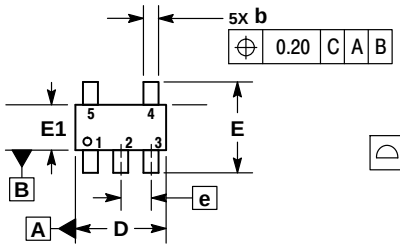
ON Semiconductor®

SC−74A
CASE 318BQ
ISSUE B

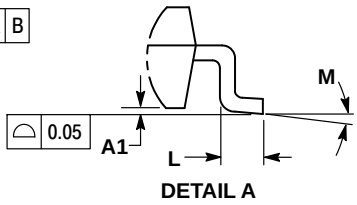
DATE 18 JAN 2018



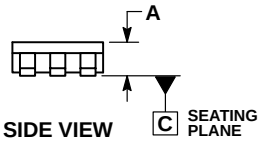
SCALE 2:1



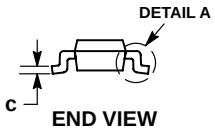
TOP VIEW



DETAIL A



SIDE VIEW

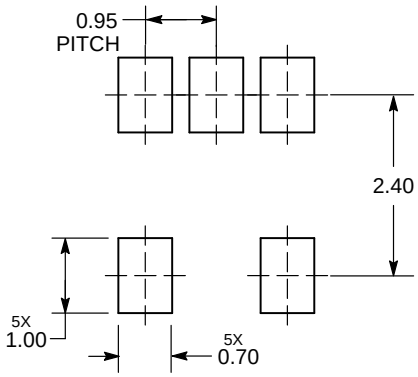


END VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

	MILLIMETERS	
DIM	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0 °	10 °

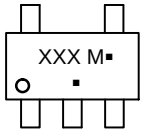
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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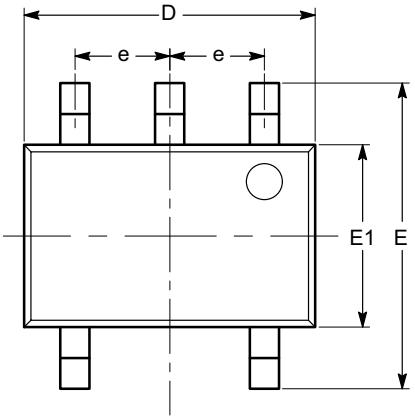
STATUS:	**ON SEMICONDUCTOR STANDARD**		
NEW STANDARD:			
DESCRIPTION:	**SC−74A**		**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ BY I. HYLAND.	27 JUN 2017
A	CORRECTED MARKING DIAGRAM FROM 6 TO 5−LEAD. REQ BY I. HYLAND.	20 SEP 2017
B	CORRECTED SOLDERING FOOTPRINT PITCH FROM 3.40MM TO 2.40MM. REQ. BY I. HYLAND.	18 JAN 2018

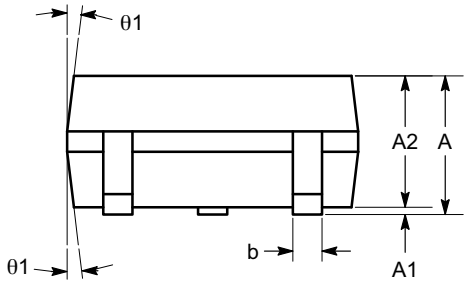
SC−88A (SC−70 5 Lead), 1.25x2
CASE 419AC−01
ISSUE A

DATE 29 JUN 2010

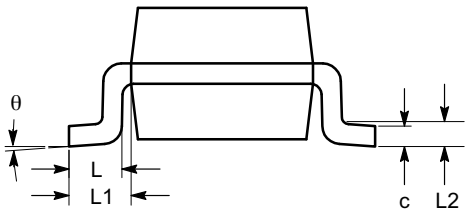


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°



SIDE VIEW



END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

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DESCRIPTION:	**SC−88A (SC−70 5 LEAD), 1.25X2**		**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

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ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT
North American Technical Support:
Voice Mail: 1 800−282−9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

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